N-Channel 45 V (D-S) MOSFET

PRODUCT SUMMARY			
V_{DS} (V)	$R_{DS(on)}$ (mΩ)(Typ.)	I_D (A)[a,c]	Q_g (Typ.)
45	2.5 at V_{GS} = 10 V	110	138 nC
	3.2 at V_{GS} = 4.5 V	100	

FEATURES

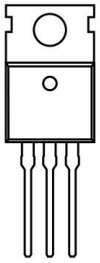
- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested

RoHS COMPLIANT

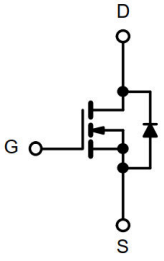
APPLICATIONS

- Synchronous Rectification
- Power Supplies

TO-220 Pin Configuration



G D S
Top View



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)				
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	45	V
Gate-Source Voltage		V_{GS}	± 25	
Continuous Drain Current (T_J = 175 °C)	T_C = 25 °C	I_D	110[a,c]	A
	T_C = 70 °C		100[c]	
	T_A = 25 °C		29[b]	
	T_A = 70 °C		23[b]	
Pulsed Drain Current		I_{DM}	350	
Avalanche Current Pulse	L = 0.1 mH	I_{AS}	80	
Single Pulse Avalanche Energy		E_{AS}	320	mJ
Continuous Source-Drain Diode Current	T_C = 25 °C	I_S	110[a,c]	A
	T_A = 25 °C		2.6[b]	
Maximum Power Dissipation	T_C = 25 °C	P_D	312[a]	W
	T_C = 70 °C		200	
	T_A = 25 °C		3.13[b]	
	T_A = 70 °C		2.0[b]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient[b]	t < 10 s	R_{thJA}	32	40	°C/W
Maximum Junction-to-Case	Steady State	R_{thJC}	0.33	0.4	

Notes:
a. Based on T_C = 25 °C.
b. Surface Mounted on 1" x 1" FR4 board.
c. Calculated based on maximum junction temperature. Package limitation current is 110 A.

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
Parameter	**Symbol**	**Test Conditions**	**Min .**	**Typ.**	**Max.**	**Unit**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	45			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = 250 µA		41		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 8.0		
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	1.0		3.0	V
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 40 V, V_{GS} = 0 V			1	µA
		V_{DS} = 40 V, V_{GS} = 0 V, T_J = 55 °C			10	
On-State Drain Current[a]	$I_{D(on)}$	V_{DS} ≥ 5 V, V_{GS} = 10 V	110			A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 30 A		2.5	3.0	mΩ
		V_{GS} = 4.5 V, I_D = 20 A		3.2	3.8	
Forward Transconductance[a]	g_{fs}	V_{DS} = 15 V, I_D = 30 A		180		S
Dynamic[b]						
Input Capacitance	C_{iss}	V_{DS} = 20 V, V_{GS} = 0 V, f = 1 MHz		6760		pF
Output Capacitance	C_{oss}			602		
Reverse Transfer Capacitance	C_{rss}			625		
Total Gate Charge	Q_g	V_{DS} = 20 V, V_{GS} = 10 V, I_D = 30 A		138		nC
Gate-Source Charge	Q_{gs}			12		
Gate-Drain Charge	Q_{gd}			25		
Gate Resistance	R_g	f = 1 MHz		1.0		Ω
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 20 V, R_L = 1.0 Ω I_D ≅ 30 A, V_{GEN} = 10 V, R_g = 1 Ω		22		ns
Rise Time	t_r			13		
Turn-Off Delay Time	$t_{d(off)}$			79		
Fall Time	t_f			11		
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 20 V, R_L = 1.0 Ω I_D ≅ 30 A, V_{GEN} = 4.5 V, R_g = 1 Ω		104		
Rise Time	t_r			64		
Turn-Off Delay Time	$t_{d(off)}$			180		
Fall Time	t_f			61		
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C			110	A
Pulse Diode Forward Current[a]	I_{SM}				350	
Body Diode Voltage	V_{SD}	I_S = 1 A		0.6	1	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = 30 A, di/dt = 100 A/µs, T_J = 25 °C		51		ns
Body Diode Reverse Recovery Charge	Q_{rr}			65		nC
Reverse Recovery Fall Time	t_a			32		ns
Reverse Recovery Rise Time	t_b			21		

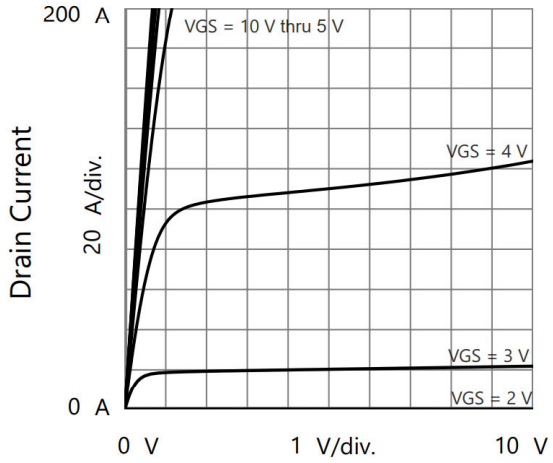
Notes:

a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.

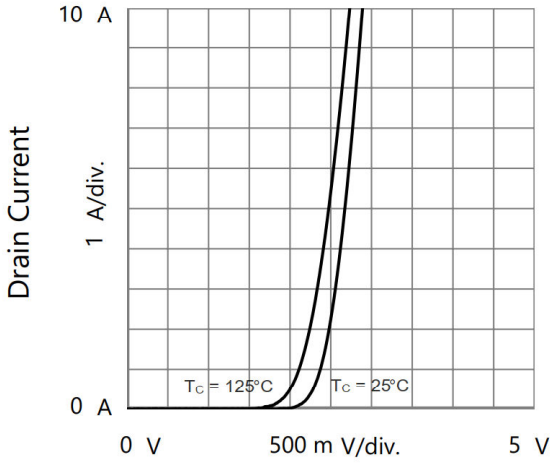
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

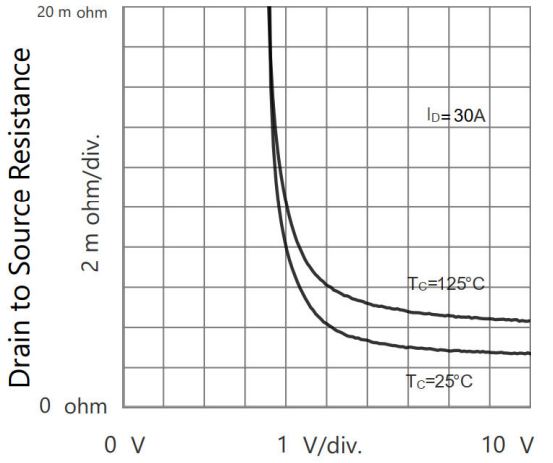
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



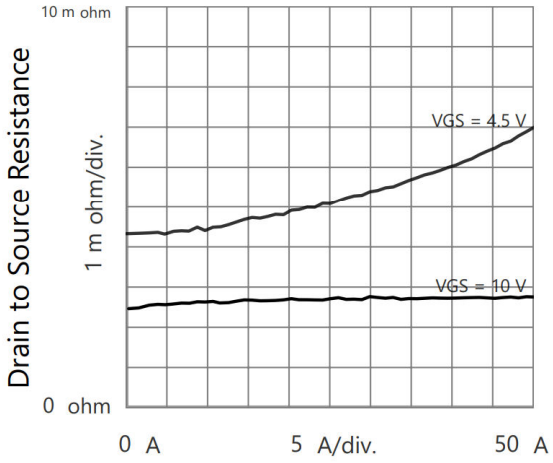
Drain to Source Voltage
Output Characteristics



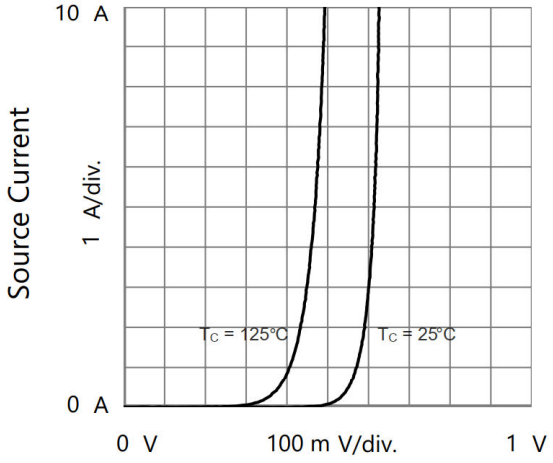
Gate to Source Voltage
Transfer Characteristics



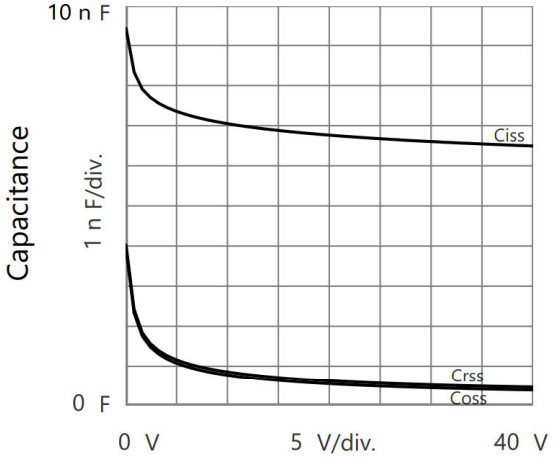
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltage



Drain Current
Drain to Source Resistance vs. Drain Current

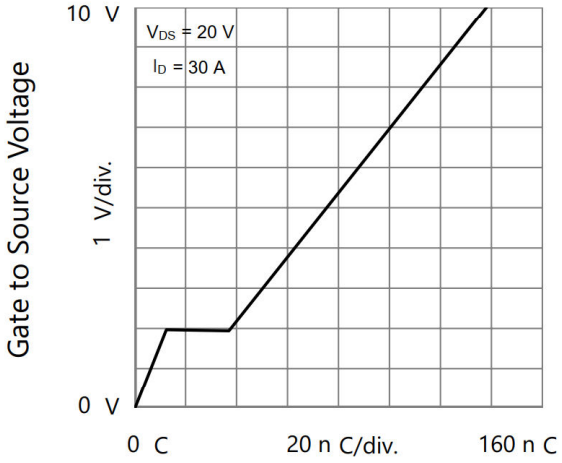


Source to Drain Voltage
Body Diode Forward Characteristics

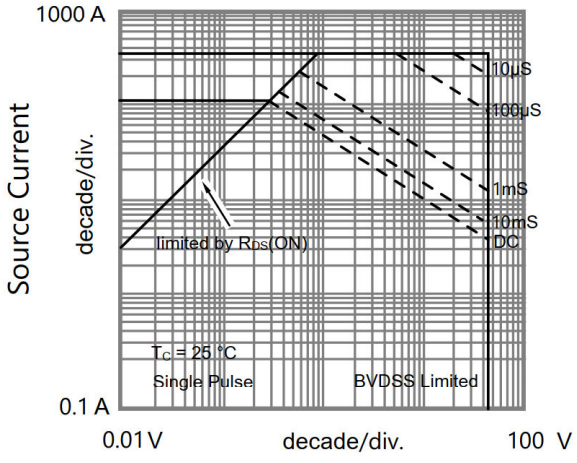


Drain to Source Voltage
Capacitances

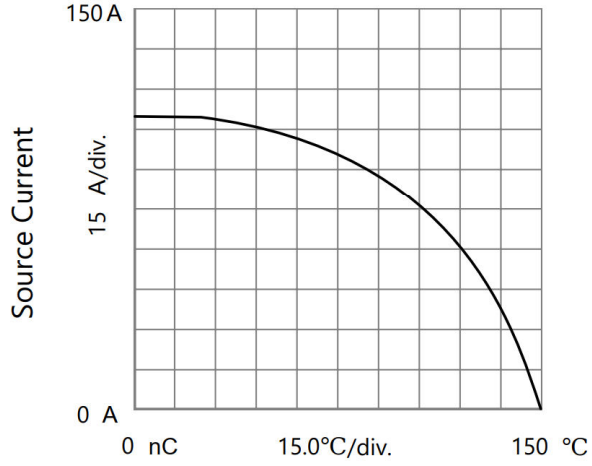
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



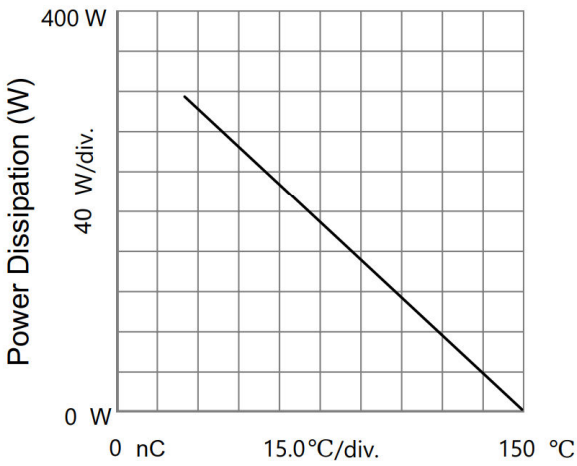
Gate to Source Voltage vs. GateCharge



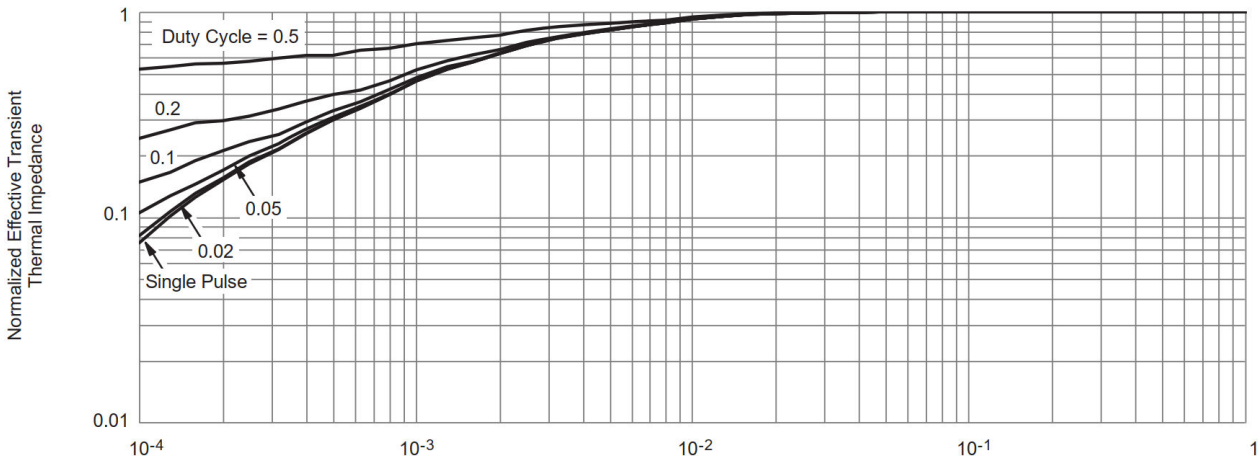
Safe Operating Area, Junction-to-Ambient



Current Derating



Power Derating



Normalized Thermal Transient Impedance, Junction-to-Case

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